

Surface Mount Fuses

High-Current > 881 Series

Temperature Re-rating Curve



Note:

1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Example:

For continuous operation at 70°C, the fuse should be re-rated as follows: I = (0.75)(0.90)I_{RAT} = (0.675)I_{RAT}

The temperature re-rating curve represents nominal conditions. For questions about the temperature re-rating curve, please consult Littlefuse technical support assistance.



Soldering Parameters

Reflow Condition		Pb – Free assembly
Number of allowed reflow cycles		3
Pre Heat	- Temperature Min (T _{s(min)})	150°C
	- Temperature Max (T _{s(max)})	200°C
	-Time (Min to Max) (t _s)	60 - 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max.
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T _L) (Liquidus)	217°C
	- Temperature (t _L)	60 - 150 seconds
Peak Temperature (T _P)		260+0/-5 °C
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C





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6 oz. (210µm) minimum Cu layer Recommended Pad Layout

Part Numbering System



60 amp product is 0881<u>060.</u>UR (100 amp product shown above).

Product Characteristics

Materials	Body: Thermoplastic, RTI 150°C Terminations: Tin-plated Copper	
Product Marking	Brand logo, Voltage Rating, and Ampere Rating	
Operating Temperature	-55° to +100°C with proper derating	

Notes:

1. Based on loading at 75% of ampere rating when mounted using recommended pad layout. Usage outside of stated operating temperature range requires testing in application. Maintain case temperature below 150°C in application.

Thermal Shock	MIL-Std 202 Method 107 Test Condition B (-65°C to 125°C, 5 cycles).		
Moisture Resistance MIL-Std 202 method 106 High Humidity (90-98%RH), Heat (65°C)			
Vibration	MIL-STD-202, Method 201 (10-55 Hz)		
Mechanical Shock	MILSTD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)		
Resistance to Solder Heat	MIL-Std 202 Method 210 Test Condition B (10sec at 260°C)		
Solderability	MIL-STD-202 Method 208		
MSL Test	Level 1 J-STD-020		
Salt Fog	MIL-Std 202 Method 101 Test Condition B (5% NaCL solution, 48 hours exposure)		

Packaging							
Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code				
24mm Tape and Reel	EIA-481 Rev. D (IEC 60286, part 3)	500	UR				

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Application testing is strongly recommended. Specifications are subject to change without notice. Revised: 06/26/19